

**PATENT ASSIGNMENT**

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Wen-Kun YANG	04/07/2011
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	King Dragon International Inc.
<b>Street Address:</b>	Wickhams Cay P.O. Box 662 Road Town,
<b>City:</b>	Tortola
<b>State/Country:</b>	BRITISH VIRGIN ISLANDS
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	12855705
<b>CORRESPONDENCE DATA</b>	
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<b>ATTORNEY DOCKET NUMBER:</b>	TF10HMK021
<b>NAME OF SUBMITTER:</b>	Chih Feng YEH
<b>Total Attachments: 1</b> source=TF10HMK021P2192230Asmt#page1.tif	

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ATTORNEY/DOCKET NO:

**ASSIGNMENT BY INVENTOR(S) OF U.S. APPLICATION**

WHEREAS, I am the original, first and sole inventor and I own (if only one name is listed below) or an original, first and joint inventor and the joint inventors own (if plural names are listed below) (referred to as "ASSIGNOR" below) the subject matter which is claimed and for which a patent is sought on the invention (referred to as the "INVENTION" below) entitled:

Title: **Semiconductor Device Package Structure and Method for the Same**

the specification of which (check one):

- is executed on even date herewith.
- was filed on (day-month-year) 13/8/2010 as U.S. Application Number 12/855,705
- was filed on (day-month-year) as PCT Application Number
- was executed on the following date(s) (day-month-year)

WHEREAS, **King Dragon International Inc.**

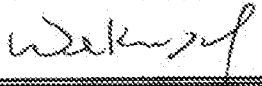
having a postal address of **Wickhams Cay P.O. Box 662 Road Town, Tortola, British Virgin Islands**

(referred to as "ASSIGNEE" below) desires to acquire the entire right, title and interest in and to the same in the U.S.;

NOW, THEREFORE, for good and valuable consideration, the receipt and adequacy of which is hereby acknowledged, ASSIGNOR, by these presents does sell, assign and transfer unto ASSIGNEE, the entire right, title, and interest in and to said INVENTION and application throughout the United States of America, including any and all patents granted on any division, continuation, continuation-in-part and reissue of said application.

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent applications in the United States for said INVENTION, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said INVENTION, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE's expense, to identify and communicate to ASSIGNEE at ASSIGNEE's request documents and information concerning the INVENTION that are within ASSIGNOR's possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR's obligations under this instrument shall extend to ASSIGNOR's heirs, executors, administrators and other legal representatives.

ALSO, ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all patents referred to above to ASSIGNEE, as the ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE's sole use and behoof; and for the use and behoof of ASSIGNEE's legal representatives and successors, to the full end of the term for which such patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

Full Name of First or Sole Inventor <b>Wen-Kun YANG</b>	First Office Address <b>No. 47, Lane 6, An-Kang St., Hsin-Chu City, Taiwan, R.O.C.</b>
Citizenship <b>Taiwan, R.O.C.</b>	Residence (city, and either state or foreign country, MPEP §605.02) <b>Hsin-Chu City, Taiwan, R.O.C.</b>
Date <b>Apr. 7, 2011</b>	Signature 

See following page(s) for additional joint inventors.

(06/Nov/2001)